

LINEAR TECHNOLOGY MATERIALS DECLARATION

(Engineering Calculation)

TSSOP Exp. Pad

LT3012HFE#PBF

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TOTAL MASS (g): 0.067339

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002515	1000000	52196.6445312		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.025576	975000	37810.09375		
		Iron (Fe)	7439-89-6	0.000630	24000	9355.66015625		
		Phosphorus (P)	7723-14-0	0.000008	300	118.802032471		
		Zinc (Zn)	7440-66-6	0.000018	700	267.304959847		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead Frame Total:				0.026232	1000000	389551.875
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.002364	1000000	35104.6640625		
External Plating Total:						0.002364	1000000	35104.6640625
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.001030	1000000	15295.7626953		
Internal Plating Total:						0.001030	1000000	15295.7626953
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001034	750000	15355.1621094		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000145	250000	5123.3378962		
		Die Attach Total:				0.001179	1000000	20478.5019531
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.001348	103000	49718.6523438
				Bromine (Br)	40093-93-8	0.000000	0	0
Silica (SiO2)	60676-86-0			0.029088	895000	431964.1875		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.000065	2000	965.266540527		
Encapsulation Total:						0.032501	1000000	482648.125
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000318	1000000	4722.38085938		

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